

AccessionIndex: TCD-SCSS-T.20141120.006

Accession Date: 20-Nov-2014

Accession By: Dr.Brian Coghlan

Object name: Interdata I/O Extension Chassis

Vintage: c.1970

Synopsis: I/O extension chassis for Interdata Model 70 in this collection. S/N: ???.

Description:

This item is a 19" rackmountable I/O extension chassis for the Interdata Model 70 in this collection, see elsewhere in this catalog. It contains three I/O boards: two are standard Interdata serial line interfaces, and the other is an Interdata customisable wire-wrap board.

This chassis was purchased by the Dept.Mechanical Engineering in TCD and used by Dr.Arthur Dexter (of that department) for industrial boiler monitoring, analysis and control experiments, and the wire-wrap board contains small-scale logic circuitry used for this purpose.

The Model 70 itself was also used by Dr.Neville Harris of the Dept.Computer Science for teaching assembly language to 1st year engineers. For a teaching aid he wrote a simulator for the Interdata assembly language that ran on the department's Burroughs B1700. In 1980 both the Interdata Model 70 and its I/O Extension Chassis were moved to the Dept.Computer Science for use by Dr.Brian Coghlan.

Accession Index	Object with Identification
TCD-SCSS-T.20141120.006.01	Interdata I/O Extension Chassis. S/N: ???
TCD-SCSS-T.20141120.006.02	Interdata Serial Line Interface (1). S/N: ???
TCD-SCSS-T.20141120.006.03	Interdata Serial Line Interface (2). S/N: ???
TCD-SCSS-T.20141120.006.04	Interdata Wire-Wrap Prototyping Board.. S/N: ???
TCD-SCSS-T.20141120.006.05	Interdata Dual Serial Line Cable.

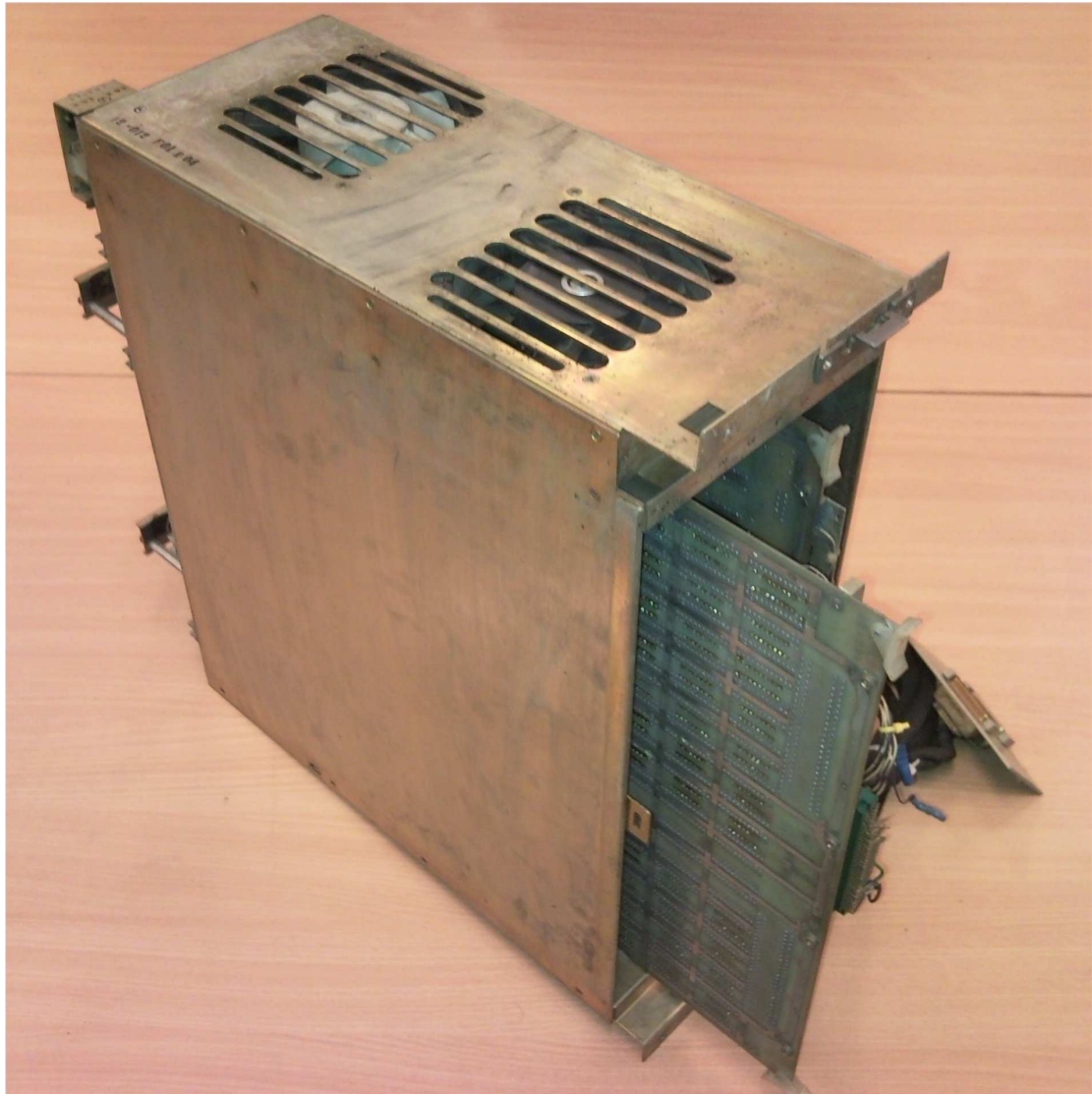


Figure 1: Interdata I/O Extension Chassis left front view



Figure 2: Interdata I/O Extension Chassis right front view

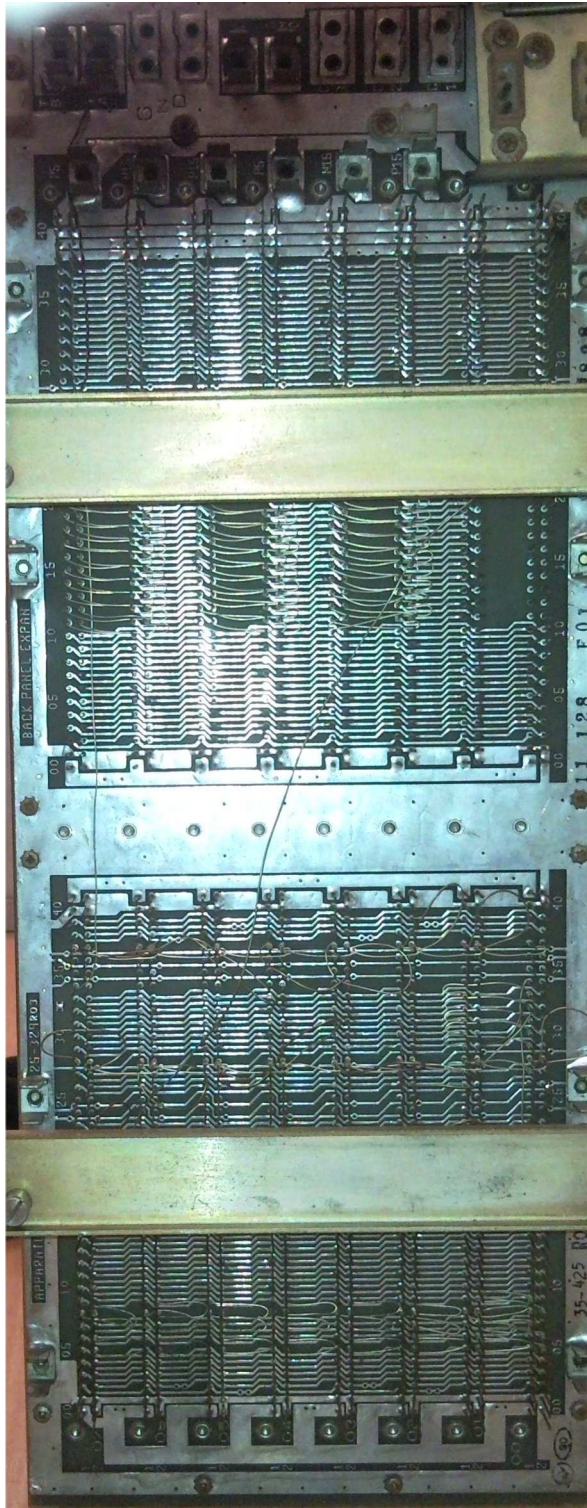


Figure 3: Interdata I/O Extension Chassis rear view

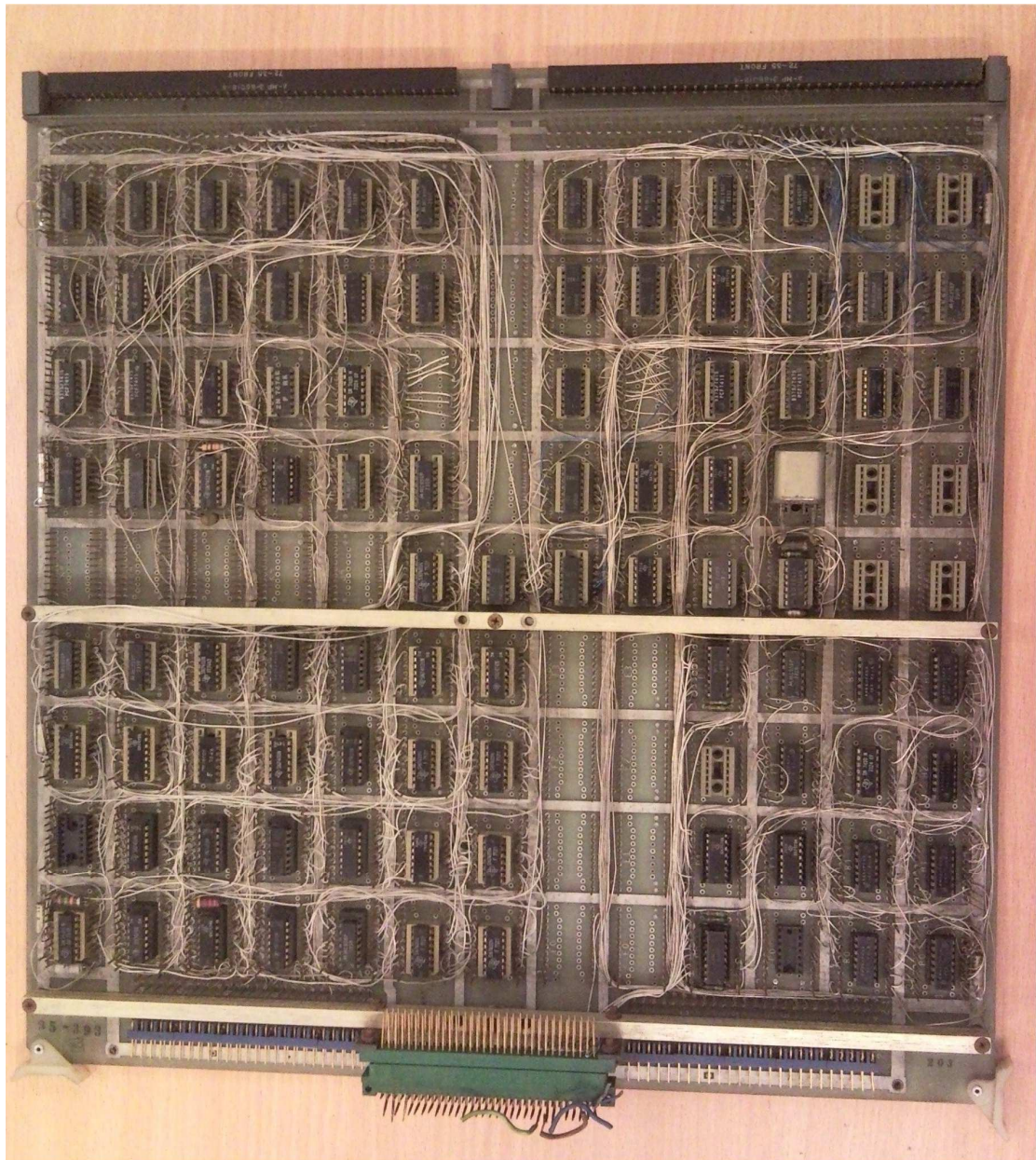


Figure 4: Interdata I/O Extension Chassis custom wire-wrap board

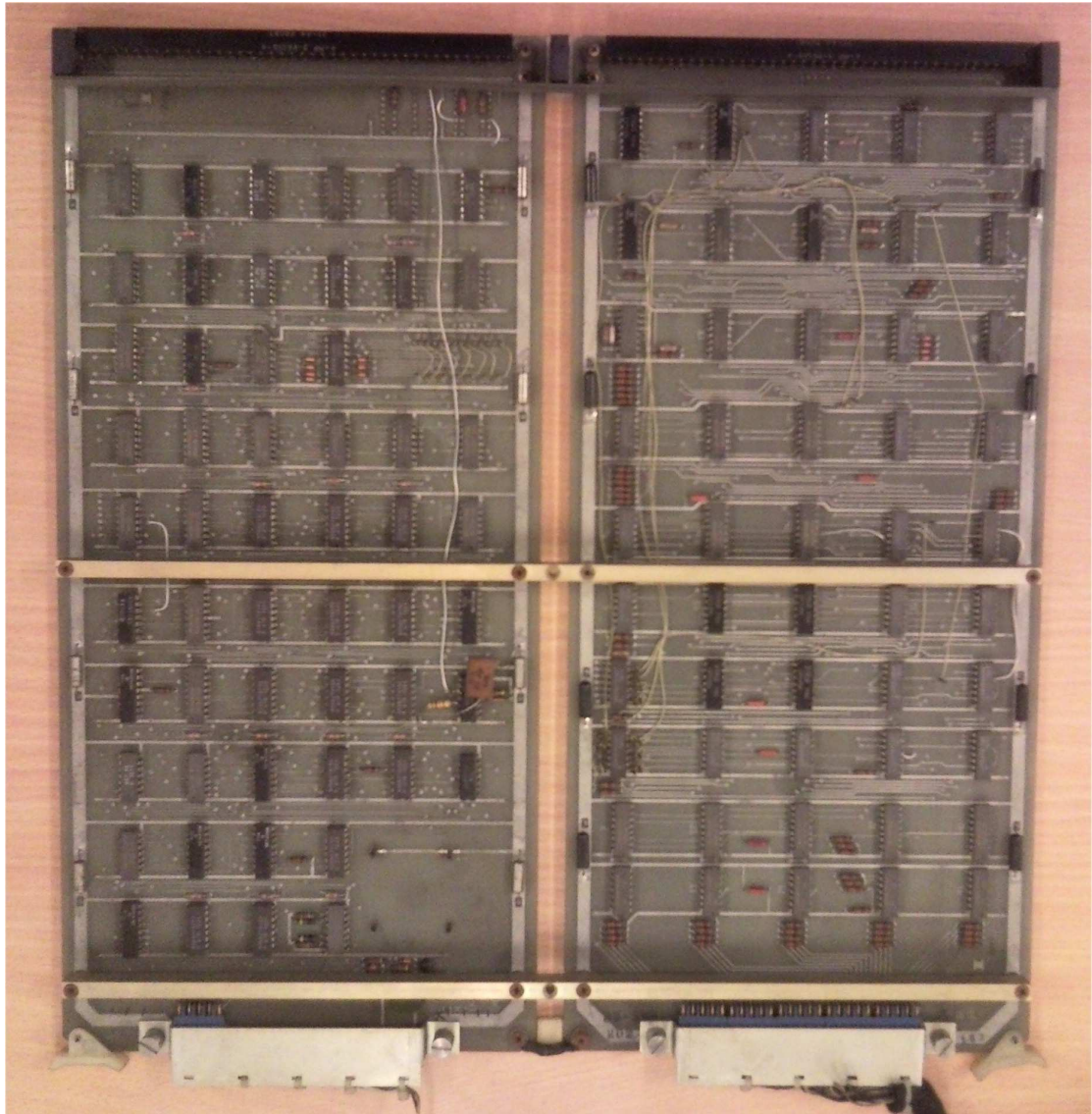


Figure 5: Interdata I/O Extension Chassis dual RS232C serial line interface